



LC895199K

ATAPI / IDE-Interface CD-ROM Error Correction IC

Preliminary

Functions

- CD-ROM ECC function, Subcode read function, ATA-PI (IDE) I/F (register block, etc.), CAV audio function

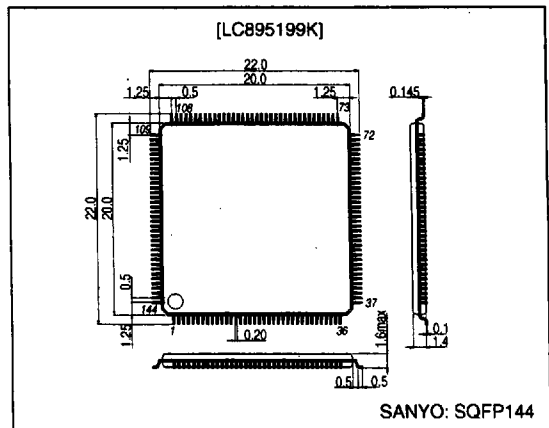
Features

- Built-in ATAPI (IDE) I/F
- 32x speed supported using EDO-DRAM (x16, 50 ns) 16.6 Mbytes/s (with IORDY) Operating frequency: 33.8688 MHz
- 32x speed supported using EDO-DRAM (x16, 45 ns) 16.6 Mbytes/s (without IORDY) Operating frequency: 33.8688 MHz
- 24x speed supported using EDO-DRAM (x16, 50 ns) 16.6 Mbytes/s (without IORDY) Operating frequency: 33.8688 MHz
- 1 Mbit to 4 Mbits of buffer RAM connectable in case of DRAM
- CD main channel, C2 flag, and subcode areas in buffer RAM can be freely set by user
- Built-in batch transfer function (function for sending CD main channel, C2 flag, subcode, etc. at one time)
- Built-in multi block transfer function (function for sending several blocks at one time)
- Built-in CAV audio function
- Built-in intelligent functions (auto buffering, auto decoding, CD-R support, etc.)
- Built-in subcode P to W buffering function (NO-ECC) and CD-TEXT support
- Ultra DMA, MODE2, MODE1, MODE0 support

Package Dimensions

unit: mm

3214-SQFP144



Specifications

Absolute Maximum Ratings at $V_{SS} = 0$ V

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	$V_{DD\ max}$	$T_a = 25^\circ\text{C}$	-0.3 to +7.0	V
Input/output voltage	$V_{I/O}$	$T_a = 25^\circ\text{C}$	-0.3 to $V_{DD} + 0.3$	V
Allowable power dissipation	$P_d\ max$	$T_a \leq 70^\circ\text{C}$	550	mW
Operating temperature	T_{opr}		-30 to +70	$^\circ\text{C}$
Storage temperature	T_{stg}		-55 to +125	$^\circ\text{C}$
Soldering temperature (pin part only)		10 s	235	$^\circ\text{C}$
Input/output power	I_i, I_o		± 20	mA

Note: * Per 1 input/output reference cell

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Allowable Operating Range at Ta = -30 to +70°C, VSS = 0 V

IO cell 5.0 V supply voltage

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Supply voltage	VDD		4.5	5.0	5.5	V
Input voltage range	VIN		0		VDD	V

Internal cell 3.3 V supply voltage

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Supply voltage	VDD		3.0	3.3	3.6	V
Input voltage range	VIN		0		VDD	V

DC Characteristics at Ta = -30 to +70°C, VSS = 0 V, VDD = 4.5 to 5.5 V

Parameter	Symbol	Conditions	Ratings			Unit	Applicable pins *1
			min	typ	max		
High-level input voltage	V _{IH}	TTL levels	2.2	—	—	V	(1)
Low-level input voltage	V _{IL}		—	—	0.8	V	
High-level input voltage	V _{IH}	TTL levels	2.2	—	—	V	(10)
Low-level input voltage	V _{IL}	with pull-down resistor	—	—	0.8	V	
High-level input voltage	V _{IH}	TTL levels	2.4	—	—	V	(2), (3), (11)
Low-level input voltage	V _{IL}	Schmitt	—	—	0.8	V	
High-level output voltage	V _{OH}	I _{OH1} = -4 mA	VDD - 2.1	—	—	V	(4)
Low-level output voltage	V _{OL}	I _{OL1} = 4 mA	—	—	0.4	V	
High-level output voltage	V _{OH}	I _{OH1} = -8 mA	VDD - 2.1	—	—	V	(10), (12)
Low-level output voltage	V _{OL}	I _{OL1} = 8 mA	—	—	0.4	V	
High-level output voltage	V _{OH}	I _{OH1} = -12 mA	VDD - 2.1	—	—	V	(5)
Low-level output voltage	V _{OL}	I _{OL1} = 12 mA	—	—	0.4	V	
High-level output voltage	V _{OH}	I _{OH1} = -12 mA	VDD - 2.1	—	—	V	(5)
Low-level output voltage	V _{OL}	I _{OL1} = 12 mA	—	—	0.4	V	
High-level output voltage	V _{OH}	I _{OH1} = -4 mA	VDD - 2.1	—	—	V	(8), (11)
Low-level output voltage	V _{OL}	I _{OL1} = 24 mA	—	—	0.4	V	
Low-level output voltage	V _{OL}	I _{OL1} = 24 mA	—	—	0.4	V	(9)
Low-level output voltage	V _{OL}	I _{OL1} = 8 mA	—	—	0.4	V	(6), (7)
Input leak current	I _{IL}	V _I = V _{SS} , V _{DD}	-10		+10	μA	(1), (2), (3), (11)
Output leak current	I _{OZ}	During high-impedance output	-10		+10	μA	(6), (8), (9), (11)
Pull-up resistance	R _{UP}		40	80	160	kΩ	(10)
Pull-up resistance	R _{UP}		20	40	80	kΩ	(7), ZDMACK *2

Note: *1 The applicable pin sets are as follows.

*2 When ZDMACK is reset, internal pull-up resistor is OFF.

When Config-Reg-R46 (PULON)-bit 0 (ZDMACK) = 1, pull-up resistor becomes ON.

INPUT

- (1) ATPINSEL, CSCTRL, SUA0 to 6, BCK, C2PO, LRCK, SDATA, SBSO, SCOR, WFCK, TEST0 to 1
- (2) ZRESET, ZCS, ZRD, ZWR, CSEL
- (3) DA0 to 2, ZCS1FX, ZCS3FX, ZDIOR, ZDIOW, ZDMACK, ZHRST

OUTPUT

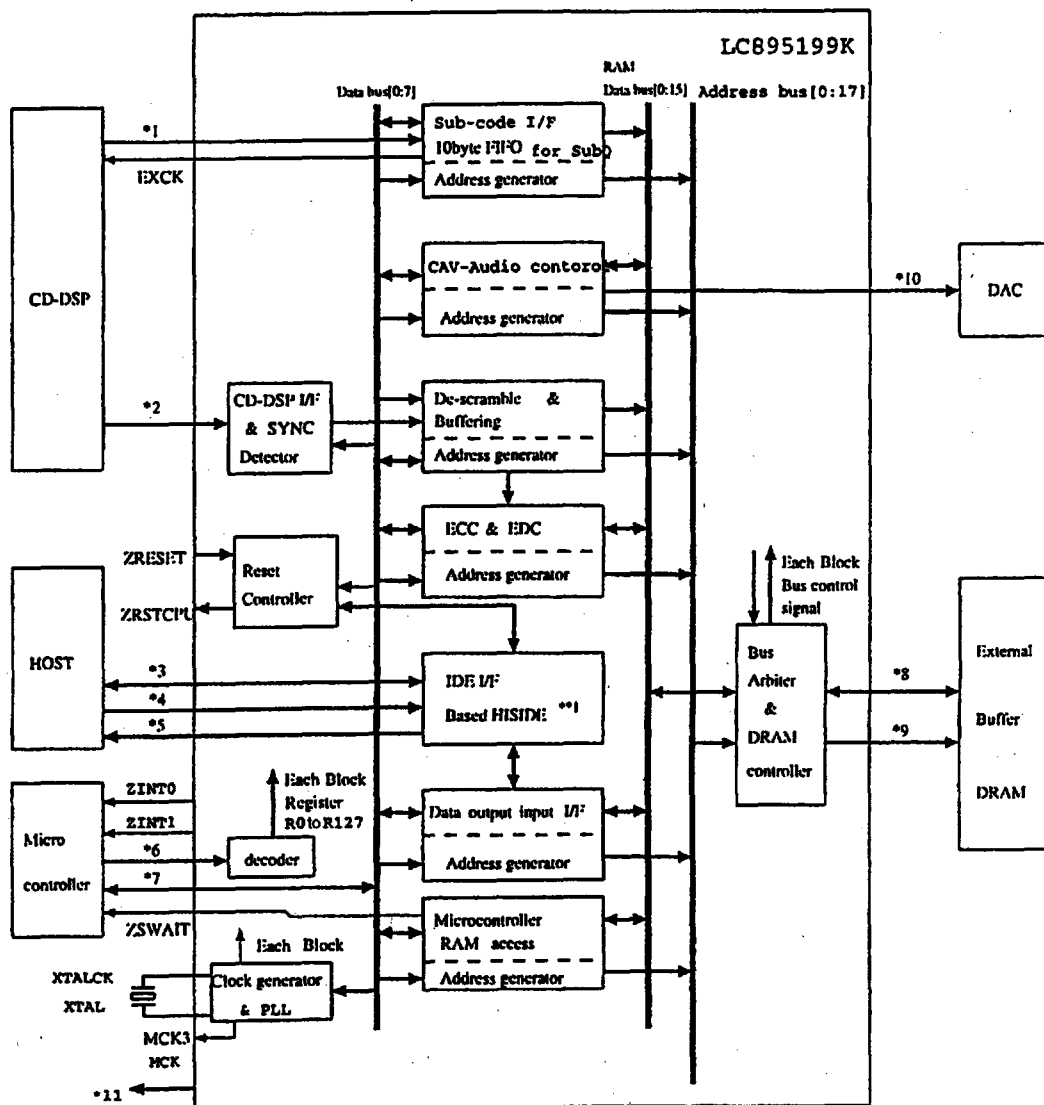
- (4) RA0 to 8, ZRAS0, ZCAS0 to 1, ZUWE, ZLWE, ZOE
- (5) MCK, MCK3
- (6) ZRSTCPU
- (7) ZINT, ZINT1, ZSWAIT
- (8) DMARQ, HINTRQ
- (9) IORDY, ZIOCS16

INOUT

- (10) D0 to 7, IO0 to 15, HDB0 to 7
- (11) DD0 to 15, ZDASP, ZPDIAG
- (12) EXCK

Note: Pins XTAL and XTALCK are not included in the DC characteristics.

Block Diagram



- *1 WFCK, SBSO, SCOR
- *2 BCK, SDATA, LRCK, C2PO
- *3 DD0 to DD15, ZDASP, ZPDIAG
- *4 ZCS1FX, ZCS3FX, DA0 to 2, ZDIOR, ZDIOW, ZDMACK, CSEL
- *5 DMARQ, HINTRQ, ZIOCS16, IORDY, ZHRST
- *6 ZRD, ZWR, SUA0 to 6, ZCS, CSCTRL
- *7 D0 to D7
- *8 IO0 to IO15
- *9 RA0 to RA8, ZRAS0, ZCAS0, ZCAS1, ZOE, ZUWE, ZLWE
- *10 DBCK, DLCK, DSDATA
- *11 IOP0 to IOP7
- **1 HISIDE(WD25C32) is made by WESTERN DIGITAL